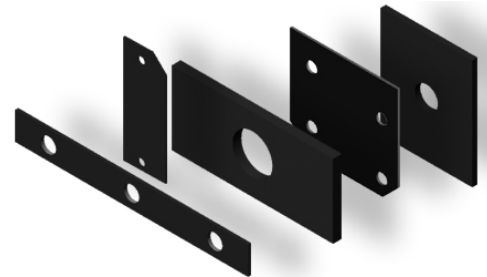


COOLPOLY® THERMALLY CONDUCTIVE PLASTICS

FOR SUBSTRATES AND ELECTRONIC PACKAGING

CoolPoly thermally conductive injection molding grade thermoplastics are ideal low cost substitutes for ceramic substrates and other electronic packaging components. Historically, ceramics have been common electronic substrate materials due to a combination of dielectric properties and thermal conductivity. CoolPoly D5108 thermally conductive plastic has been shown in commercial applications to represent up to a 50% cost reduction versus an alumina substrate while providing equivalent heat transfer.



Thermally conductive plastics offer:

- LOW COST, EXCELLENT HEAT TRANSFER
- DESIGN AND MANUFACTURING FLEXIBILITY
- SIMILAR DIELECTRIC, PHYSICAL AND THERMAL PROPERTIES TO ALUMINA

Net shape, 3-dimensional injection molding of thermally conductive plastics meets electronic packaging suppliers' goals of miniaturization, integration and speed while significantly reducing the time, temperature, complexity and cost of the manufacturing process.